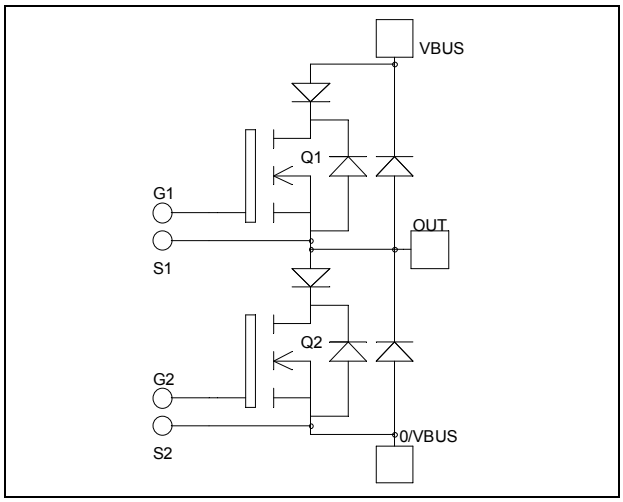
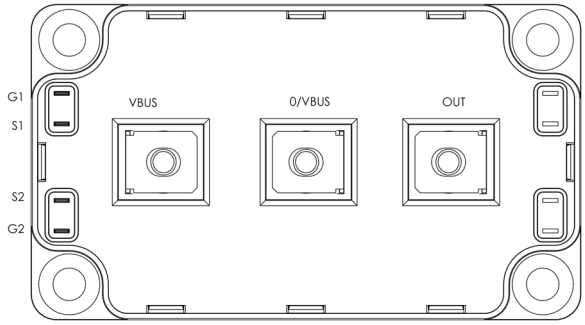
APTM20AM06SG

Phase leg
Series & parallel diodes
MOSFET Power Module

V_{DSS} = 200V
R_{DSon} = 6mΩ typ @ Tj = 25°C
I_D = 300A @ Tc = 25°C





Application

- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7® MOSFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Fast intrinsic reverse diode
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		200	V
I_D	Continuous Drain Current	T_c = 25°C	300	A
		T_c = 80°C	225	
I_{DM}	Pulsed Drain current		1200	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		7.2	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	1250	W
I_{AR}	Avalanche current (repetitive and non repetitive)		24	A
E_{AR}	Repetitive Avalanche Energy		30	mJ
E_{AS}	Single Pulse Avalanche Energy		1300	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V, V_{DS} = 200V	T_j = 25°C			500	µA
		V_{GS} = 0V, V_{DS} = 160V	T_j = 125°C			2000	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 150A			6	7.2	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 6mA		3		5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V, V_{DS} = 0V				±500	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		18.5		nF
C_{oss}	Output Capacitance			6.03		
C_{rss}	Reverse Transfer Capacitance			0.58		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 100V I_D = 300A		325		nC
Q_{gs}	Gate – Source Charge			144		
Q_{gd}	Gate – Drain Charge			156		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 133V I_D = 300A R_G = 0.8Ω		28		ns
T_r	Rise Time			56		
$T_{d(off)}$	Turn-off Delay Time			81		
T_f	Fall Time			99		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 25°C** V_{GS} = 15V, V_{Bus} = 133V I_D = 300A, R_G = 0.8Ω		1543		µJ
E_{off}	Turn-off Switching Energy			1517		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 133V I_D = 300A, R_G = 0.8Ω		2027		µJ
E_{off}	Turn-off Switching Energy			1770		

Series diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			200			V
I_{RM}	Maximum Reverse Leakage Current	V_R=200V	T_j = 25°C			350	µA
			T_j = 125°C			600	
I_F	DC Forward Current		T_c = 85°C		120		A
V_F	Diode Forward Voltage	I_F = 120A			1.1	1.15	V
		I_F = 240A			1.4		
		I_F = 120A	T_j = 125°C		0.9		
t_{rr}	Reverse Recovery Time	I_F = 120A V_R = 133V di/dt = 400A/µs	T_j = 25°C		31		ns
			T_j = 125°C		60		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		120		nC
			T_j = 125°C		500		

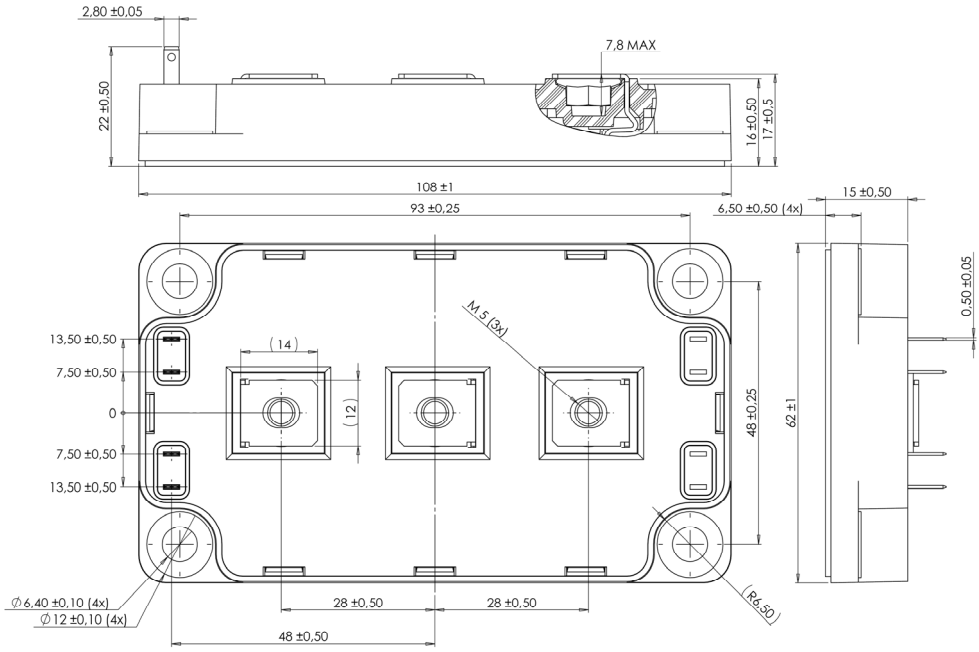
Parallel diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			200			V
I_{RM}	Maximum Reverse Leakage Current	V_R=200V	T_j = 25°C			350	µA
			T_j = 125°C			600	
I_F	DC Forward Current		T_c = 85°C		120		A
V_F	Diode Forward Voltage	I_F = 120A			1.1	1.15	V
		I_F = 240A			1.4		
		I_F = 120A	T_j = 125°C		0.9		
t_{rr}	Reverse Recovery Time	I_F = 120A V_R = 133V di/dt = 400A/µs	T_j = 25°C		31		ns
			T_j = 125°C		60		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		120		nC
			T_j = 125°C		500		

Thermal and package characteristics

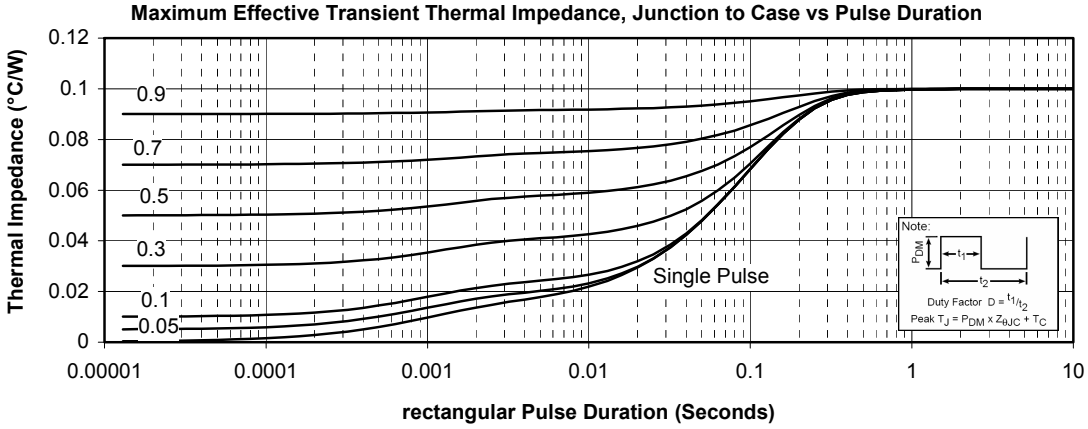
Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance	Transistor				0.10	°C/W
		Series diode				0.46	
		Diode parallel				0.46	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_J	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

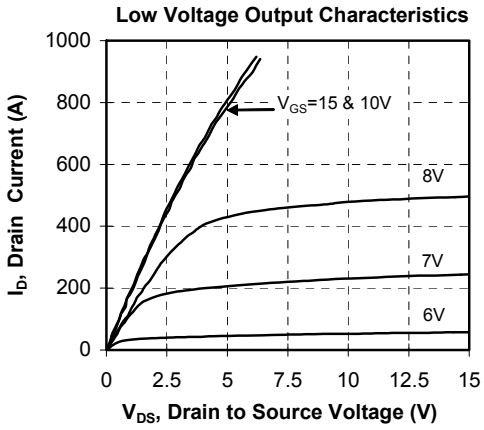
SP6 Package outline (dimensions in mm)

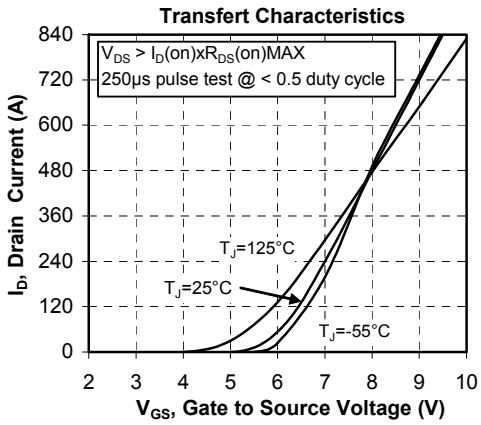


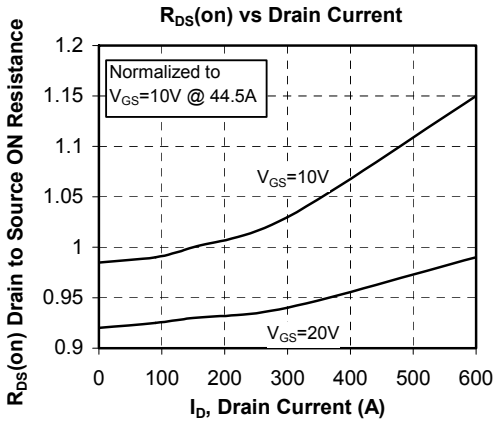
See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

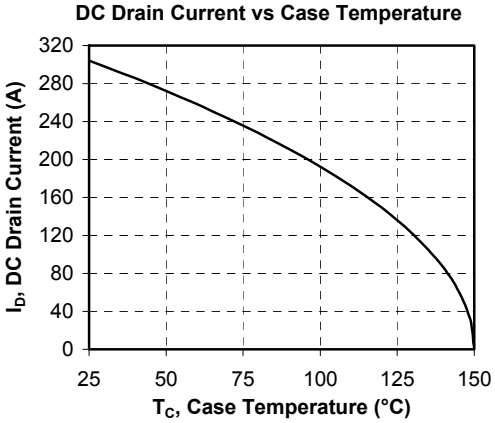
Typical Performance Curve

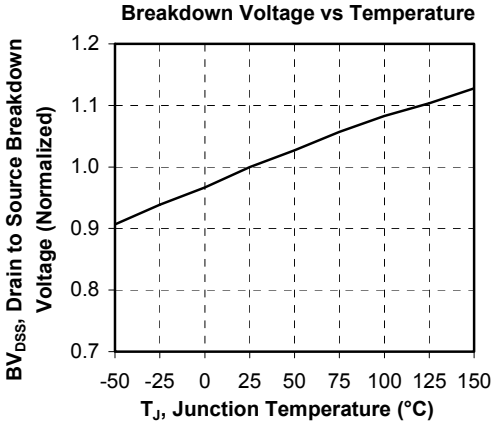


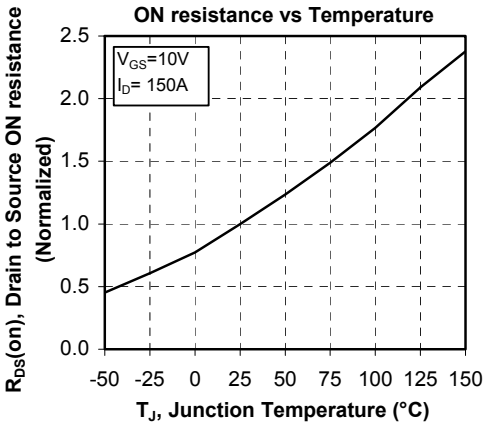


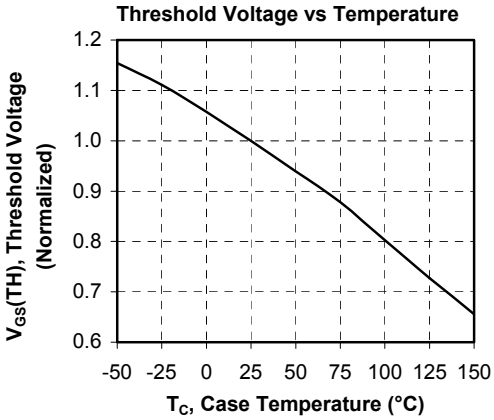


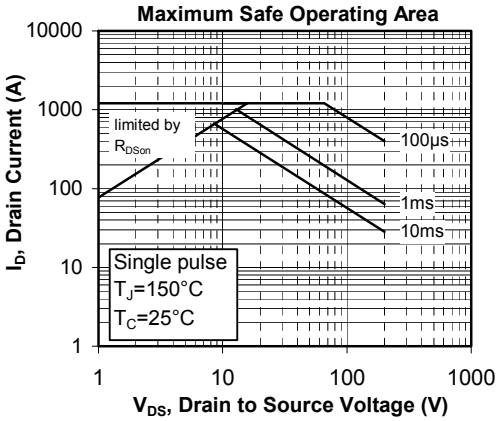


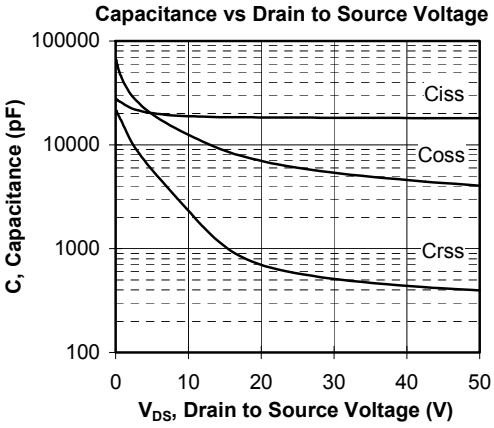


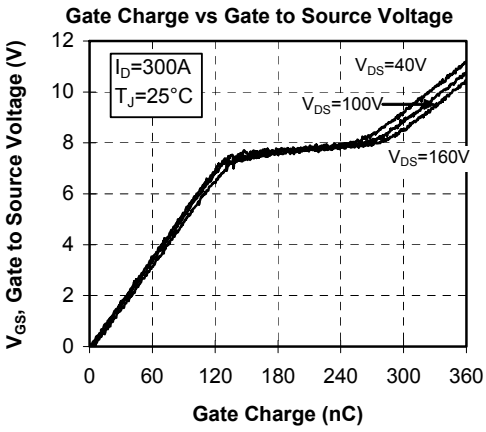

Breakdown Voltage vs Temperature
BVDSS, Drain to Source Breakdown Voltage (Normalized)
1.2
1.1
1.0
0.9
0.8
0.7
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)


ON resistance vs Temperature
RDS(on), Drain to Source ON resistance (Normalized)
VGS=10V
ID= 150A
2.5
2.0
1.5
1.0
0.5
0.0
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)

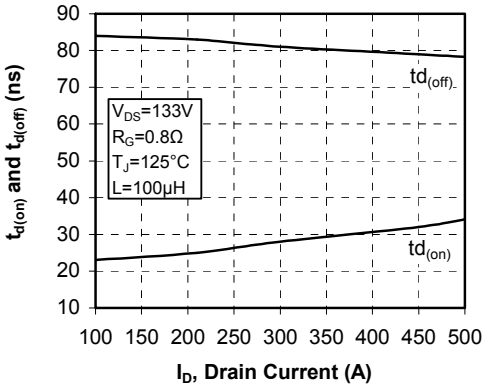

Threshold Voltage vs Temperature
VGS(TH), Threshold Voltage (Normalized)
1.2
1.1
1.0
0.9
0.8
0.7
0.6
-50 -25 0 25 50 75 100 125 150
TC, Case Temperature (°C)


Maximum Safe Operating Area
ID, Drain Current (A)
10000
1000
100
10
1
limited by RDSon
100µs
1ms
10ms
Single pulse
TJ=150°C
TC=25°C
1
10
100
1000
VDS, Drain to Source Voltage (V)

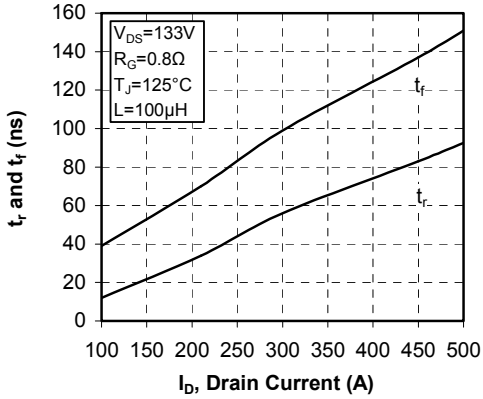

Capacitance vs Drain to Source Voltage
C, Capacitance (pF)
100000
10000
1000
100
Ciss
Coss
Crss
0 10 20 30 40 50
VDS, Drain to Source Voltage (V)


Gate Charge vs Gate to Source Voltage
VGS, Gate to Source Voltage (V)
12
10
8
6
4
2
0
ID=300A
TJ=25°C
VDS=40V
VDS=100V
VDS=160V
0 60 120 180 240 300 360
Gate Charge (nC)

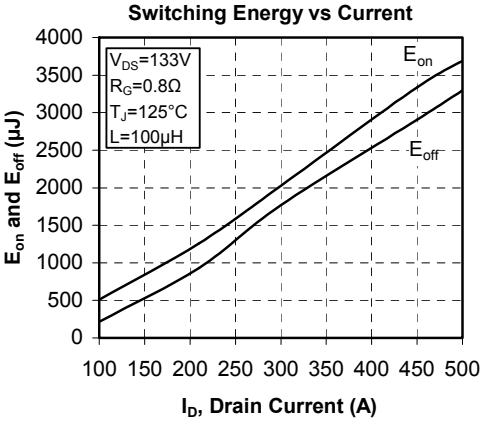
Delay Times vs Current



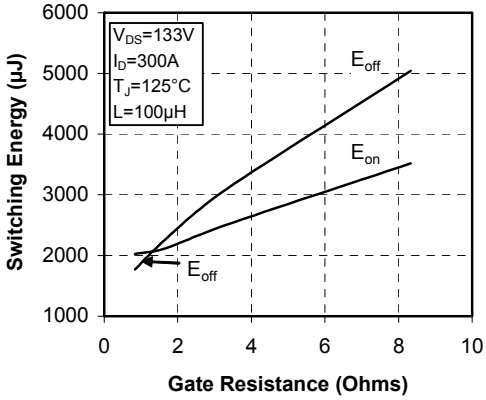
Rise and Fall times vs Current



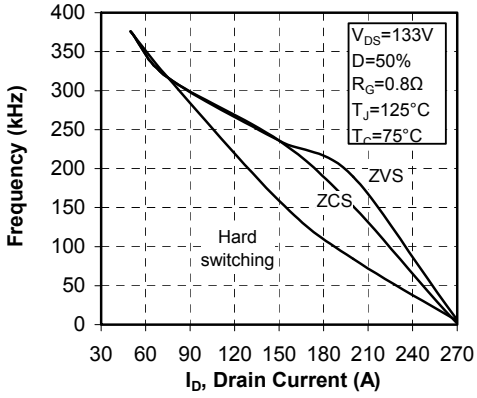
Switching Energy vs Current



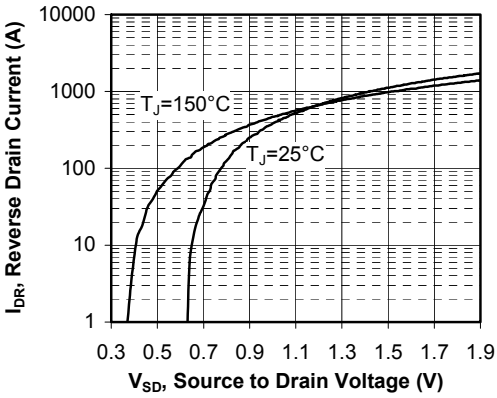
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



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